AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently Amended) An IC card, comprising:

a first support;

a second support;

an IC module including an IC chip, a reinforcing structural member neighboring to the IC chip and an antenna; the IC module provided between the first and second supports;

a first adhesive layer provided between the first support and the reinforcing structural member; and

a second adhesive layer provided between the second support and the IC chip;

wherein when the IC card is curved with a radius R1 of curvature, the following formula is satisfied:

R1 < R1' < R2 ≤ R3

where R1' is a radius of curvature of an outermost layer of the IC card, R2 is a radius of curvature of the reinforcing structural member, and R3 is a radius of curvature of the IC chip, and

wherein the reinforcing structural member is a metallic reinforcing plate having an upper surface on which the IC chip is mounted and an area of the upper surface of the metallic reinforcing plate is larger than an area of the IC chip, and

wherein when θ is an angle between the upper surface of the metallic reinforcing plate and a line connecting an edge of the upper surface of the metallic reinforcing plate with an edge of an upper surface of the IC chip, the following formula is satisfied:

$0.02 < \tan θ < 0.2$.

2. (Original) The IC card of claim 1, wherein when D1 is a thickness of the first adhesive layer and T1 is the maximum length of the reinforcing structural member, D1/T1 is 0.001 to 0.05.

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3. (Currently Amended) The IC card of claim 2, wherein D1/T1 is 0.002 to 0.04.

4. (Canceled)

5. (Currently Amended) The IC card of claim 1 [[4]], wherein the following formula is satisfied:

$$0.03 < \tan\theta < 0.15.$$

6. (Original) The IC card of claim 1, wherein when D2 is a thickness of the second adhesive layer and T1 is the maximum length of the reinforcing structural member, D2/T1 is 0.001 to 0.05.

7. (Original) The IC card of claim 6, wherein D2/T1 is 0.002 to 0.04.

8. (Original) The IC card of claim 1, wherein the first and second adhesive layers have a 2% modulus of elasticity of 5 kg/mm^2 to 55 kg/mm^2 and a ductility at a breaking point of 200% to 1300%.

9. (Original) The IC card of claim 8, wherein the 2% modulus of elasticity is 6 kg/mm^2 to 50 kg/mm^2.

10. (Original) The IC card of claim 1, wherein the reinforcing structural member has a Young's modulus of 150 Gpa to 450 Gpa.

11. (Original) The IC card of claim 1, wherein the IC card has a thickness of 5 μm to 100 μm.

12. (Original) The IC card of claim 1, wherein an image receiving layer is provided on the first support.

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13. (Currently Amended) The IC card of claim 1, wherein [[and]] a writable layer is provided on the second support.

14. (Original) The IC card of claim 1, wherein the first and second adhesive layer is formed by a reactive-type hot-melt adhesive.

15. (New) The IC card of claim 2, wherein the following formula is satisfied:

$$0.03 < \tan \theta < 0.15.$$

16. (New) The IC card of claim 15, wherein when D2 is a thickness of the second adhesive layer and T1 is the maximum length of the reinforcing structural member, D2/T1 is 0.001 to 0.05.

17. (New) The IC card of claim 16, wherein D2/T1 is 0.002 to 0.04.

18. (New) The IC card of claim 2, wherein the first and second adhesive layer is formed by a reactive-type hot-melt adhesive.

19. (New) The IC card of claim 3, wherein the following formula is satisfied:

$$0.03 < \tan \theta < 0.15.$$

20. (New) The IC card of claim 11, wherein the reinforcing structural member has a Young's modulus of 150 Gpa to 450 Gpa.

21. (New) The IC card of claim 20, wherein the first and second adhesive layer is formed by a reactive-type hot-melt adhesive.